

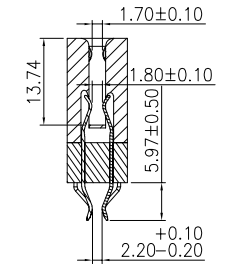
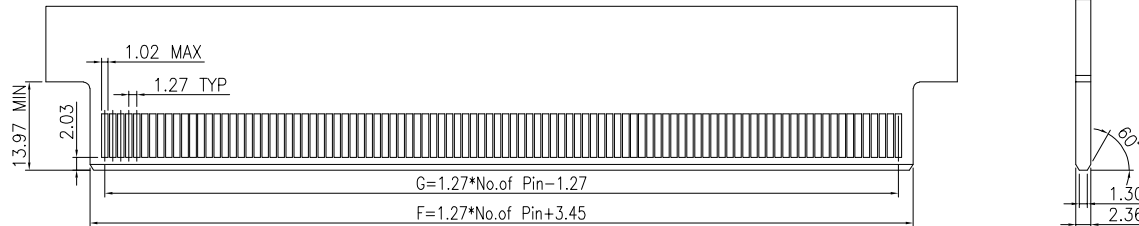
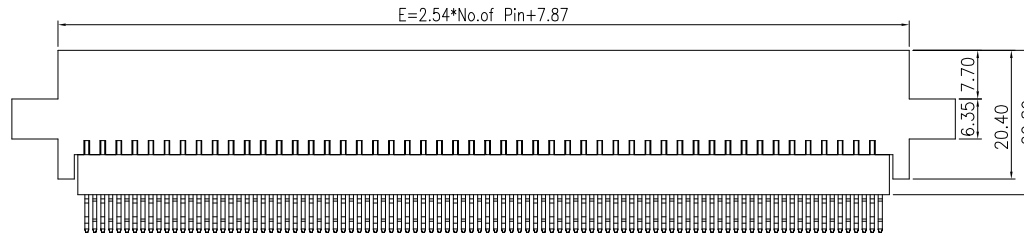
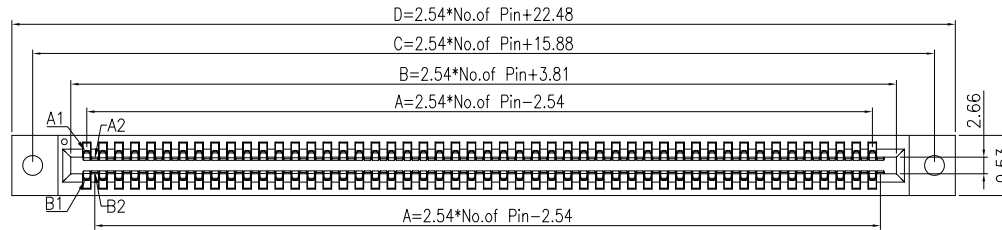
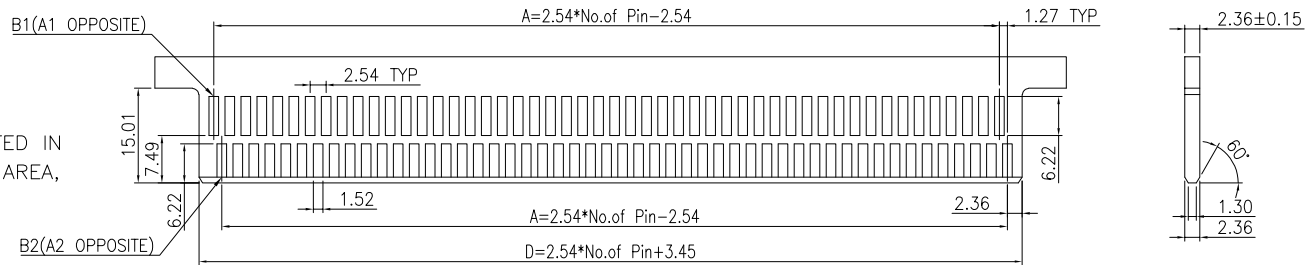
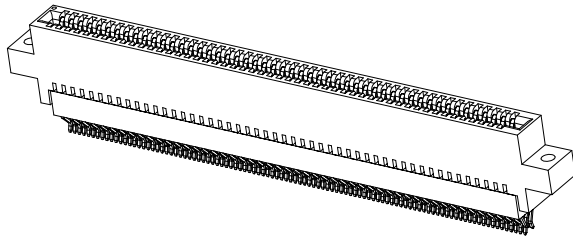
客户图

NOTES:

- .FINISH:
 1.1 HOUSING: Polyester(PA9T),UL94 V-0
 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 2.1 CURRENT RATING: 3.0 AMP,AC/DC
 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 125V,AC/Minute
 2.3 CONTACT RESISTANCE: 100mΩ MAX.
 2.4 INSULATION RESISTANCE: 1000 mΩ Min
 2.6 Operation Temperature:-55°C to +150°C
- 3.SALT SPRAY TEST:
 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 40S
- 5.ORDER INFORMATION:

61F4-J-200-SX-228-C 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
040=4*10PIN	S0=Gold Tin	228=22.89mm	R=REEL
120=4*30PIN	S1=1u" Gold/Tin		C=TRAY
200=4*50PIN	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		



RECOMMENDED PCB LAYOUT(TOP SIDE)
 PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2024.05.07	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2024.05.07				
A1	2024.12.20	修改弹高及夹口尺寸	Mr.Zeng		X.XX ±0.25	CHECK	Jack	2024.05.07	SIZE	A4	PART NO.	61F4-J-200-SX-228-C 01
AO		NEW			X.XXX ±0.15	APPROVE	Andy	2024.05.07	SHEET	1/1	TITLE:	61F4_1.27mm 金手指 夹板式 带耳朵
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle ±3°	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1087
					DIM. TOL							

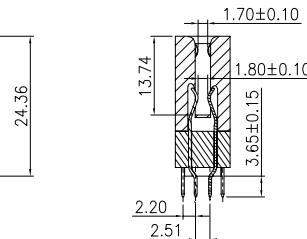
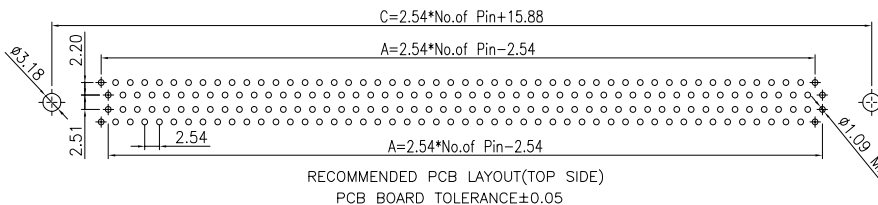
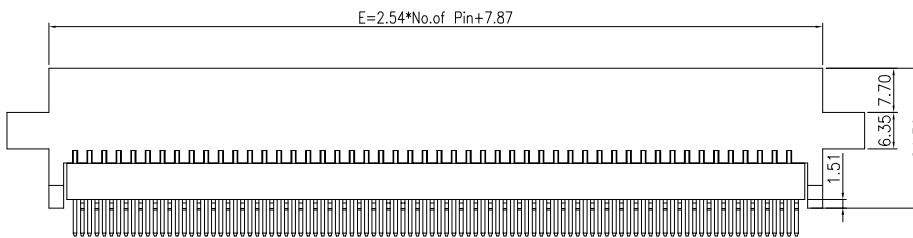
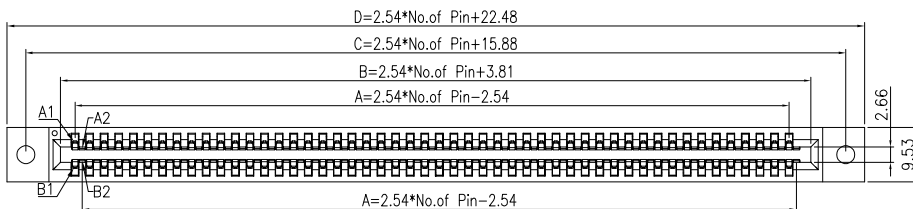
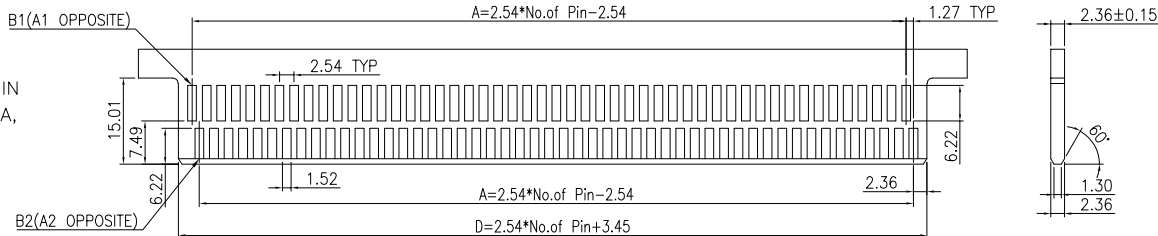
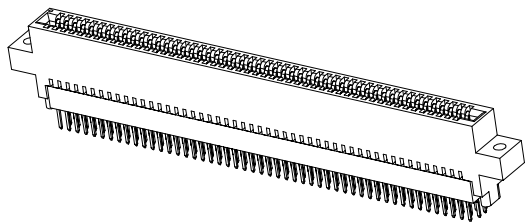
客户图

NOTES:

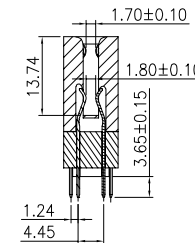
- .FINISH:
 1.1 HOUSING: Polyester(PA9T),UL94 V-0
 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 2.1 CURRENT RATING: 3.0 AMP,AC/DC
 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 125V,AC/Minute
 2.3 CONTACT RESISTANCE: 100mΩ MAX.
 2.4 INSULATION RESISTANCE: 1000 mΩ Min
 2.6 Operation Temperature:-55°C to +150°C
- 3.SALT SPRAY TEST:
 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 40S
- 5.ORDER INFORMATION:

61F4-SX-200-SX-243-C 01

Pin 数码 SEE TABLE	端子电镀: S0=Gold Tin S1=1u" Gold/Tin S2=3u" Gold/Tin S3=5u" Gold/Tin S4=10u" Gold/Tin S5=15u" Gold/Tin S6=30u" Gold/Tin	塑胶高度: 243=24.36mm	流水码: 01-99	包装方式: R=REEL C=TRAY
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61F4-S1-200-SX-243-C 01



61F4-S2-200-SX-243-C 01

OPERATION		DRAW	Mr.Zeng	2024.05.07
X.X	±0.40	DESIGN	Jensen	2024.05.07
X.XX	±0.25	CHECK	Jack	2024.05.07
X.XXX	±0.15	APPROVE	Andy	2024.05.07
Angle	±3°	UNIT	mm	SCALE
DIM.	TOL	UNIT	mm	SCALE
		UNIT	mm	SCALE
		UNIT	mm	SCALE

SOLEPIN 东莞市硕品电子有限公司
 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

A1	2024.12.20	修改弹高尺寸	Mr.Zeng			SIZE	A4	PART NO.	61F4-SX-200-SX-243-C 01
AO		NEW				SHEET	1/1	TITLE:	61F4_1.27mm 金手指 DIP 180° 带耳朵
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	UNIT	PROJ.	SCALE	DRAW NO.	SP-1085

客户图

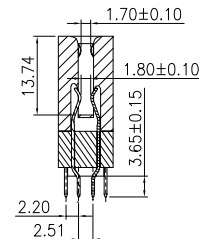
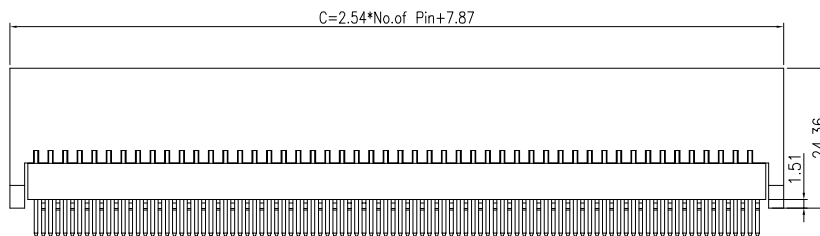
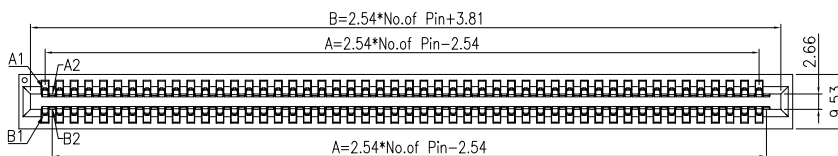
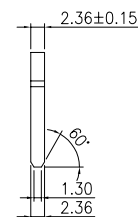
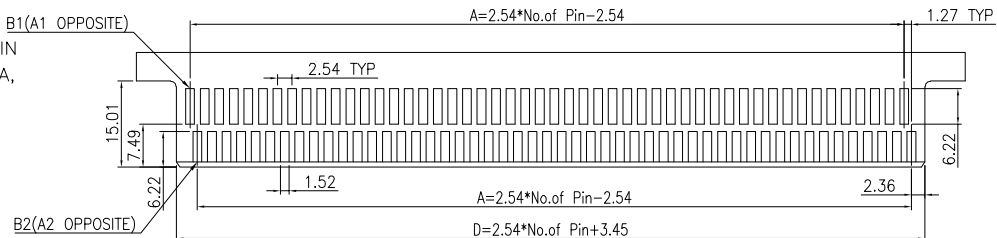
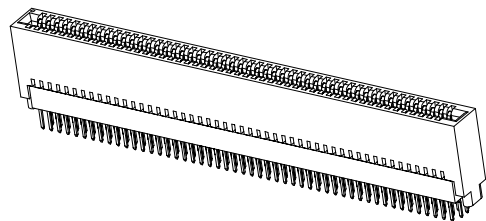
NOTES:

- .FINISH:
- HOUSING: Polyester(PA9T),UL94 V-0
 - CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
- CURRENT RATING: 3.0 AMP,AC/DC
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
 - CONTACT RESISTANCE: 30mΩ MAX.
 - INSULATION RESISTANCE: 5000 mΩ Min
 - Operating Voltage: 225 VAC
 - Operation Temperature:-55°C to +150°C
- 3.SALT SPRAY TEST:
- CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 40S
- 5.ORDER INFORMATION:

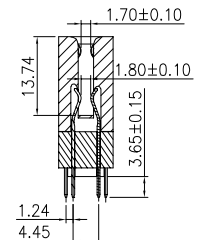
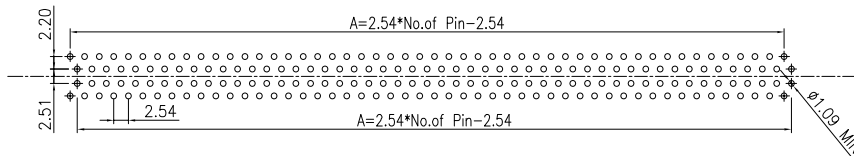
61F4W-SX-200-SX-243-C 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
040=4*10PIN	S0=Gold Tin	243=24.36mm	R=REEL
120=4*30PIN	S1=1u" Gold/Tin		C=TRAY
200=4*50PIN	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码:
01-99



61F4W-S1-200-SX-243-C 01



61F4W-S2-200-SX-243-C 01

RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2024.05.07	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X ±0.40	DESIGN	Jensen	2024.05.07					
A1	2024.12.20	修改弹高尺寸	Mr.Zeng		X.XX ±0.25	CHECK	Jack	2024.05.07	SIZE	A4	PART NO.	61F4W-SX-200-SX-243-C 01	
AO		NEW			X.XXX ±0.15	APPROVE	Andy	2024.05.07	SHEET	1/1	TITLE:	61F4 1.27mm 金手指 DIP 180° 无耳朵	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle ±3°	DIM.	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1088